



Specification:

- Electrical Characteristics:
 Contact Current Rating:0.5 Amperes.
 Dielectric Withstanding Voltage:AC500V r.m.s.
 Insulation Resistance:1000 MΩ Minimum.
 Contact Resistance:40 mΩ Maximum.
- Environmental:
 Operating Temperature:-25°C~+90°C.
- Environmental:
 Mating Cycles:5,000 Insertions.
- Mechanical Characteristics:
 Card Push Insertion/Out Force:0.2~1.40kgf.
 Contact Separation Force:0.20kgf Minimum.
- Material:
 Insulator:Hi-Temp Plastic UL 94V-0 Rated.
 Contact:Copper Alloy(t=0.15mm).
 Shell:Stainless Steel(t=0.15mm).
 Spring:SWP.
- ⊗ Make is FAI test Dimension
 ▼ Make is major test Dimension

XKTF-015-X

G= GOLD 18"
 N= NICKEL 80R"

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
④	Spring	1	SWP	
③	Shell	1	SUS	
②	Terminal	9	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ x					ANGLAR ±5°
Δ x					L ≤ 4 ±0.2
Δ x					4 < L ≤ 16 ±0.3
					16 < L ≤ 63 ±0.4
					L > 63 ±0.5

DSND	DATE	SCALE: N/A	MODEL TYPE:
DWN	DATE	VIEW:	TF CARD CONN
CHKD	DATE	UNIT: mm	PART NO.:
APPD	DATE	SIZE: A4	DWG NO.: XKTF-015-X
Kosod Technology Co., Ltd.			WEIGHT: 1.0g
			SHEET: 1/1
			REVISION: A0